

We are delighted to share with you the remarkable success of the Mini Colloquium on Advanced Technology for Inter-Chiplet Connectivity, organized by the Mid Hudson Valley EPS Chapter on June 21, 2023. This event held at the SUNY CNSE / IBM Research Campus in Albany, New York, brought together students and professionals from various backgrounds, regardless of their IEEE or EPS membership status.

The Mini Colloquium aimed to shed light on the latest trends in semiconductor packaging within the New York region, and we were privileged to have the participation of three distinguished subject matter experts and technology leaders in the field of electronic packaging. Their expertise and knowledge captivated the engaged audience throughout the session, fostering an atmosphere of learning and collaboration.

The event garnered significant attention, with a total of 76 individuals registering for the onsite in-person gathering. To ensure broad awareness, we employed a multi-faceted approach in publicizing the event. We leveraged Vtools, along with EPS and IEEE Region 1 announcements, to reach out to our target audience. Additionally, we disseminated information internally within various organizations and academic institutions via email, ensuring a wide reach for this exceptional opportunity. It is worth noting that registration for this event was open to all participants, and it was offered free of charge.

We would like to express our sincere appreciation to all the volunteers who contributed to the success of the EPS MHV Chapter. The organizing team, composed of Mukta Farooq as Chair, Katsuyuki Sakuma as Vice Chair, Aakrati Jain as Chapter Secretary, Sathya Raghavan as Treasurer, James Kelly as Program Chair, and Eric Perfecto as Membership Chair.

We are grateful to K. Pearsall and EPS for their financial support, which enabled us to bring this event to fruition. Additionally, we extend our gratitude to the instructors for delivering insightful lectures that enlightened and inspired the attendees. The positive feedback received from participants was a testament to the timeliness and relevance of the subject matter, as well as the expertise of the speakers.

The EPS MHV Chapter takes pride in the success of the Mini Colloquium on Current Trends in Semiconductor Packaging in NY Region. We are encouraged by the overwhelming response and the fruitful outcomes of this endeavor. Rest assured, we remain committed to continuing our efforts to organize impactful events in the future, fostering an environment of growth and knowledge-sharing within our community.

Thank you once again to all those who contributed, and we eagerly look forward to your continued support and participation in our future endeavors.

*Mukta Farooq, IEEE Fellow, July 6, 2023*



# Mini Colloquium on Current Trends in Semiconductor Packaging in NY Region

*Presented by*  
**2023 IEEE EPS Mid-Hudson Valley Chapter**

**Date:**

21 June 2023

**Time:**

8:45 am to 12 noon

**Location:**

CESTM Auditorium,  
Albany NanoTech Complex

**Free Registration for  
ALL!**

**Mid-session coffee  
and snacks included!**

To reserve your spot,  
please REGISTER at:

<https://events.vtools.ieee.org/m/361663>

Register using QR code:



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